

THAT WHICH IS CLAIMED IS:

1. A method of manufacturing an image sensor device of the type comprising an image sensor chip, including an image sensor array formed on a top surface thereof, mounted on a substrate and encapsulated by means of a dam wall formed on the substrate and surrounding the periphery of the sensor chip and having a transparent lid member affixed to the upper edges of said dam wall, wherein the method includes forming a barrier on the surface of said sensor chip and extending along at least a substantial part of at least one side of said sensor array between the sensor array and the dam wall.
2. A method as claimed in Claim 1, wherein said barrier is formed with a height of at least three microns.
3. A method as claimed in Claim 1, wherein said barrier surrounds said sensor array.
4. A method as claimed in Claim 1, wherein said barrier is formed during fabrication of the sensor chip.
5. A method as claimed in Claim 1, wherein said sensor chip is a color image sensor including a mosaic of color filter material overlying said sensor array, and said barrier is formed from said color filter material simultaneously with the formation of said mosaic.
6. A method as claimed in Claim 5, wherein said barrier is formed from a plurality of layers corresponding to a plurality of colors of filter material forming said mosaic.

8. An image sensor chip as claimed in Claim 7, wherein said barrier is formed with a height of at least three microns.

10. An image sensor chip as claimed in Claim 7, wherein said sensor chip is a color image sensor including a mosaic of color filter material overlying said sensor array, and said barrier is formed from said color filter material simultaneously with the formation of said mosaic.

11. An image sensor chip as claimed in Claim 10, wherein said barrier is formed from a plurality of layers corresponding to a plurality of colors of filter material forming said mosaic.

12. An image sensor device of the type comprising an image sensor chip, including an image sensor array formed on a top surface thereof, mounted on a substrate and encapsulated by means of a dam wall formed on the substrate and surrounding the periphery of the sensor chip and having a transparent lid member affixed to the upper edges of said dam wall, wherein the sensor chip includes a barrier formed on the surface thereof and extending along at least a

substantial part of at least one side of said sensor array between the sensor array and the dam wall.

13. An image sensor device as claimed in Claim 12, wherein said barrier is formed with a
5 height of at least three microns.

14. An image sensor device as claimed in Claim 12, wherein said barrier surrounds said sensor array.

15. An image sensor device as claimed in Claim 12, wherein said sensor chip is a color image sensor including a mosaic of color filter material overlying said sensor array, and said barrier is formed
5 from said color filter material simultaneously with the formation of said mosaic.

16. An image sensor device as claimed in Claim 15, wherein said barrier is formed from a plurality of layers corresponding to a plurality of colors of filter material forming said mosaic.

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